ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® Material © Copyright international	Composition De 2005. IPC, Bannockt and Pan-American co	c laration ourn, Illinois. A opyright conver	Il rights reserved u ntions.	nder both	This docume level parts, t	ent is a declaration he declaration er	on of the substan	ces within the manu ower level materials	facturer liste for which the	d item. Note: if e manufacturer	the item is an as has engineering	ssembly with low responsibility.	
	1 IPC Web Site for Information on IPC-1752 Standard Form			Form Type Distribute					Materials and	ials and Mfg Information			
upplier Information													
ompany name*	Company unique ID			1	Unique ID Authority				Response Date*				
nsemi									2024-05-02				
ontact Name	Title - Contact]	Phone - Contact*				Email - Contact*				
Product-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
uthorized Representative*	Title - Representative]	Phone - Representative*			Emai	Email - Representative*				
roduct-Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Requester Item Number Mfr Iter		n Number Mfr Item Name				Effective Date	Version	Version Manufacturing Site CP8		Weight*	UOM	Unit Type	
	FGH50N	FGH50N3 PTPIG		TPIGBT TO247 300V SMPS		2024-05-02				5456.725	mg	Each	
Ianufacturing Proccess Inf	ormation					-						·	
Terminal Plating / Grid A	Terminal Plating / Grid Array Material T		erminal Base Alloy J-STD-020 MS		L Rating	Peak Process Body Temperature Max		ature Max Time at	Peak Tempe	rature Numb	er of Reflow Cy	cles	
Matte Tin (Sn) - annealed		CU Alloy NA		NA		0 C 3		30	sec	conds 3			
omments													
or more information regarding m	aterial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	32.0	mg	Supplier	Silicon (Si)	7440-21-3		32	mg
Die Attach Solder	35.025	mg	Supplier	Silver (Ag)	7440-22-4		0.8756	mg
			А	Lead (Pb)	7439-92-1	7a	32.3981	mg
			Supplier	Tin (Sn)	7440-31-5		1.7512	mg
Lead Frame	3612.9	mg	Supplier	Zinc (Zn)	7440-66-6		1.75	mg
			В	Nickel (Ni)	7440-02-0		117.9998	mg
			Supplier	Iron (Fe)	7439-89-6		2.1	mg
			Supplier	Copper (Cu)	7440-50-8		3489.9998	mg
			Supplier	Phosphorus (P)	7723-14-0		1.05	mg
Mold Compound-Black	1739.8	mg	Supplier	2,6-dibromo-4-[1-(3-bromo-4- hydroxyphenyl)-1-methylethyl]phenol	6386-73-8		20.9	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		283.9998	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		34.9	mg
			Supplier	Carbon Black (C)	1333-86-4		17.3999	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1382.6	mg
Plating	31.0	mg	Supplier	Tin (Sn)	7440-31-5		31	mg
Wire Bond - Al	6.0	mg	Supplier	Aluminum (Al)	7429-90-5		6	mg